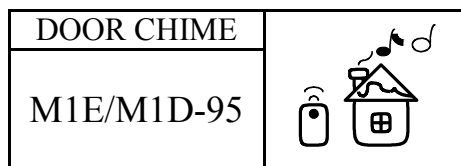




DUAL TONE
WIRELESS DOOR BELL

遥控门铃 IC



FEATURES 功能叙述

- 3 door chime sound.

M1D-95
D2 WEST MINISTER
D1 DING DING
D0 DING DONG

APPLICATION 产品应用

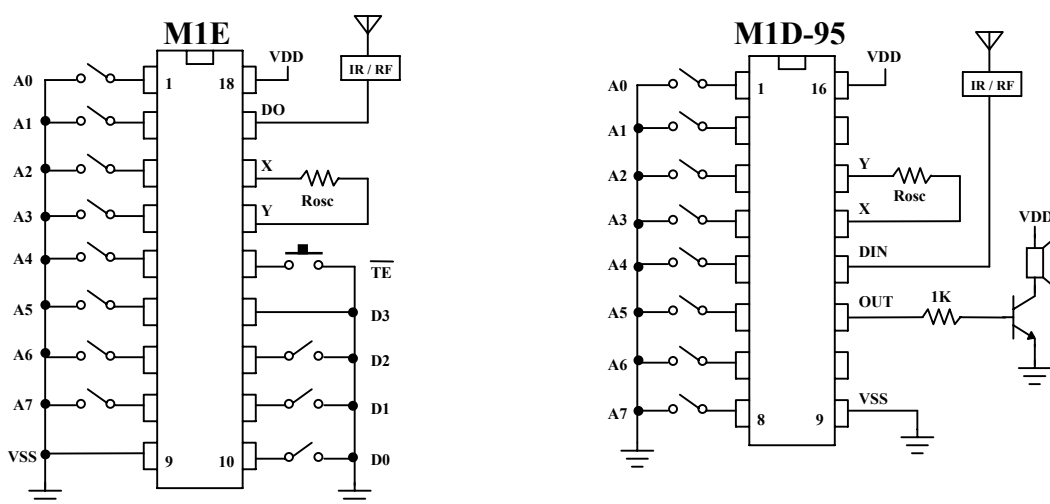
- Door bell system. 门铃系统.

ELECTRICAL CHARACTERISTICS 电气规格

(@V_{DD}=4.5V unless otherwise specified)

| Characteristics | Sym. | Min. | Typ. | Max. | Unit | REMARKS |
|----------------------------|------------------|------|------|------|------|-------------------------|
| 工作电压 Operating Voltage | V _{DD} | 2.4 | 4.5 | 5 | V | |
| 工作电流 Operating Current | I _{OP} | — | 0.3 | 1 | mA | No load |
| 静态电流 Quiescent Current | I _{SB} | — | 1 | 10 | μ A | |
| 推动电流 Driving Current | I _{OL} | 1 | — | — | mA | @ V _{DS} =1.2V |
| 振荡频率 Oscillator Frequency | F _{OSC} | — | 80 | — | KHz | External ± 30% |
| 工作温度 Operating Temperature | Temp. | 0 | 25 | 60 | °C | |

APPLICATION DIAGRAM 参考电路图



* Rosc ~ M1E : 270K Ω ; M1D-95 : 390K Ω

* All specs and applications shown above subject to change without prior notice.

(以上电路及规格仅供参考,本公司得径行修正)



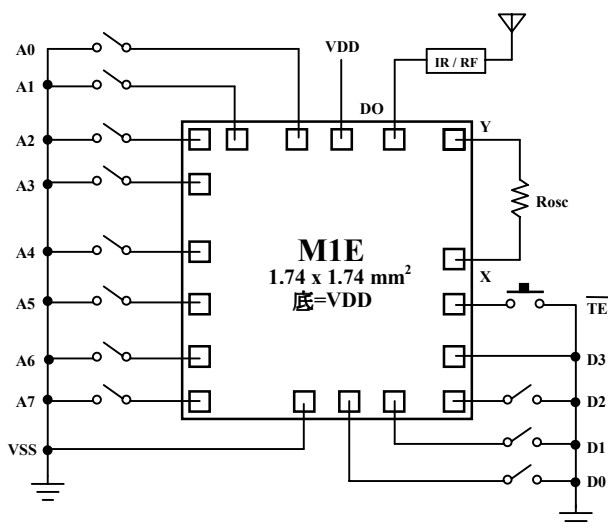
DUAL TONE
WIRELESS DOOR BELL

遙控門鈴 IC

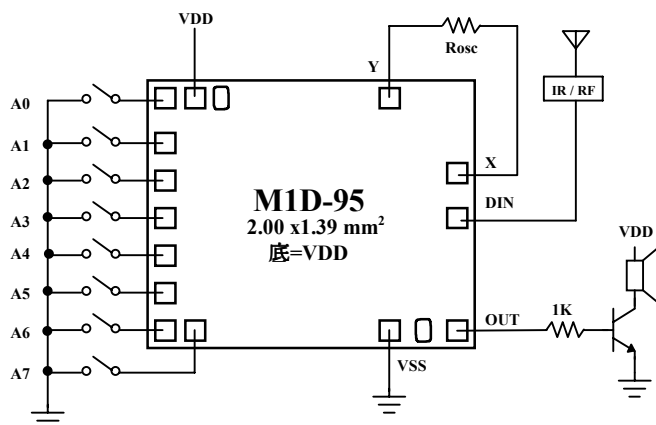
| | |
|------------|--|
| DOOR CHIME | |
| M1E/M1D-95 | |

APPLICATION DIAGRAM 参考電路圖

CHIP FORM



| SOUND | |
|-------|---------------|
| D2 | WEST MINISTER |
| D1 | DING DONG |
| D0 | DING DONG |



* Rosc ~ M1E : 270K Ω ; M1D-95 : 390K Ω

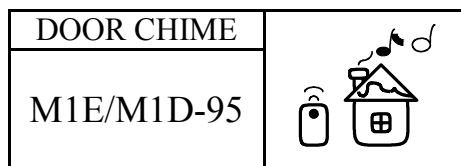
*All specs and applications shown above subject to change without prior notice.

(以上電路及規格僅供參考,本公司得徑行修正)

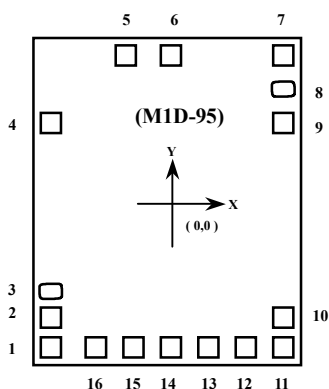


DUAL TONE
WIRELESS DOOR BELL

遙控門鈴 IC



ASSIGNMENT & POSITION



UNIT : um

| No. | NAME | X | Y |
|-----|-------|---------|---------|
| 1 | A0 | -561 | -870 |
| 2 | VDD | -560.25 | -723.75 |
| 3 | TEST3 | -562.5 | -585.75 |
| 4 | OSC2 | -560.25 | 537 |
| 5 | OSC1 | -317.25 | 870 |
| 6 | DIM | -163.5 | 869.25 |
| 7 | BZ | 559.5 | 869.25 |
| 8 | TEST | 559.5 | 636.75 |
| 9 | VSS | 559.5 | 480 |
| 10 | A7 | 559.5 | 717.75 |
| 11 | A6 | 559.5 | -872 |
| 12 | A5 | 379.5 | -867.75 |
| 13 | A4 | 198.75 | -867.75 |
| 14 | A3 | 23.25 | -868.5 |
| 15 | A2 | -150 | -867.75 |
| 16 | A1 | -325.5 | -868.5 |

* CHIP SIZE ~ 2.00 x 1.39 mm²

* IC substrate should be connected to VDD in PCB (PCB 上 IC 必須接 VDD)